



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Chw/B

In re application of

: **Confirmation No. 5253**

Kazuhiro NOBORI et al.

: Docket No. 2000_1645A

Serial No. 09/722,737

: Group Art Unit 2822

Filed November 28, 2000

: Examiner K. L. Rose

SEMICONDUCTOR PACKAGE AND
METHOD FOR FORMING
SEMICONDUCTOR PACKAGE

RESPONSE TO NOTICE OF DRAWING INCONSISTENCY WITH SPECIFICATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Sir:

Responsive to the Notice of Drawing Inconsistency With Specification mailed on November 9, 2004, the following Remarks are provided.

On April 11, 2003, an Amendment was filed which amended the substitute specification so as to make reference to new Figure 19. Since this Amendment was received by the PTO, as evidenced by the Office Action mailed June 19, 2003, only a copy of the pages of this Amendment corresponding to the changes made to the substitute specification is provided herewith. A copy of the postcard receipt is also provided.

In view of the above, it is respectfully submitted that Figure 19 is listed in the Brief Description of the Drawings in the specification, such that there is no inconsistency with the specification and drawings.

Respectfully submitted,

Kazuhiro NOBORI et al.

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November 22, 2004



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AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

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FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Sir:

Responsive to the Office Action mailed December 19, 2002, the time for responding thereto being extended for one month in accordance with a Petition for Extension submitted herewith, please amend the above-identified application as follows:

IN THE DRAWINGS:

A proposed new Figure 19, as shown in red on the attached sheet has been filed.

IN THE SUBSTITUTE SPECIFICATION:

Please replace paragraph [0013] on page 3, with the following rewritten paragraph:

In accomplishing these and other aspects, according to a first aspect of the present invention, there is provided a semiconductor package comprising:

a first semiconductor having electrodes formed on both of an upper and a lower face;

a heat radiating plate to which a lower face electrode of the first semiconductor is joined with use of a joining member; and

pillared (columnar) or spherical electrodes which are joined to upper face electrodes of the first semiconductor and the heat radiating plate, respectively.

On page 13 after line 11, insert the following new paragraph:

Fig. 19 is a schematic cross-sectional view showing connection of a lower face electrode to a heat radiating plate via solder or conductive paste.

Please replace paragraph [0060] on page 14, with the following rewritten paragraph:

In the semiconductor package according to the first embodiment of the present invention, as schematically shown in Fig. 19, a lower face electrode 50 of a semiconductor 1, having electrodes formed on both upper and lower faces, is joined to a heat radiating plate 10 with use of solder 51. Upper face electrodes 2 and 3 of the semiconductor 1, and the radiating plate 10, are joined to pillared (columnar) or spherical electrodes 11.

Please replace the Abstract of the Disclosure paragraph with the following rewritten paragraph:

Electrodes of one face of a semiconductor, which has electrodes formed on both faces, and a heat radiating plate are directly joined to quickly absorb and diffuse heat of the semiconductor, thereby improving a heat radiation effect. At the same time, electrodes on an opposite face of the semiconductor are connected to pillared electrodes that are thicker than a wire for wire bonding and larger in current capacity. These pillared electrodes can accordingly be utilized as connecting terminals to a circuit board. Ceramic is used for the heat radiating plate, so that semiconductors of different functions can be mounted simultaneously.